Wireless Ultrasonic Gas Leak Sensor

Project Title: Designed for: Public Release

Assembly Variant: 001

PCB Number: TIDA-01236
PCB Rev. E1

Variant/Label Table

<table>
<thead>
<tr>
<th>Variant</th>
<th>Label Text</th>
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<tbody>
<tr>
<td>001</td>
<td>TBD: TIDA #</td>
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- **Variant ZZ1**: PCB Label
- **Variant ZZ2**: TIDA-01236 EVM Hardware
- **Variant ZZ3**: TIDA-01236 EVM Hardware
- **Variant ZZ4**: TIDA-01236 EVM Hardware

- **Variant H1**: SJ-5303 (CLEAR)
- **Variant H2**: SJ-5303 (CLEAR)
- **Variant H3**: SJ-5303 (CLEAR)
- **Variant H4**: SJ-5303 (CLEAR)

- **Variant LBG**: Based on bill of materials, do not use. This label is for PCB labels only.

- **Variant ZZ2**: These assemblies must be clean and free from flux and all contaminants. Use of no-clean flux is not acceptable.

- **Variant ZZ3**: These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

Contact: 
http://www.ti.com/support

Wireless Ultrasonic Gas Leak Sensor

Sheet Title: TIDA-01236_EVM_Hardware.SchDoc
Size: 792.0 x 612.0
Mod. Date: 1/6/2017
File: http://www.ti.com

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Variant control disabled

SVN Rev: TIDA-01236
Number: E1
Rev: E1
TID #: TIDA-01236
Orderable: N/A
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